Call for Papers
Special Issue based on Papers from IEEE FLEPS 2021 Conference

In recent years, flexible and printable sensor systems have received substantial interest. New methods such as printing and additive manufacturing, etc. are being developed to realise a wide range of easily deployable systems such as sensors, displays, and smart tags. The technologies developed for silicon-based planar electronics and solid-state sensors are also being re-purposed to meet the demands in the emerging field of flexible and printed sensors and interfaces. This trend will continue as all market indicators point towards significant growth in this area. The growth in flexible, printed and disposable sensor technologies is also evident from the large number of papers presented at IEEE FLEPS 2021 focussing on the novel printable and solution-processable nanomaterials, and printing techniques that have brought about a new wave of novel printed sensor technologies and applications. This Special Issue will offer the authors of IEEE FLEPS 2021 an excellent opportunity to submit the extended versions of the papers presented at the conference. Authors are invited to submit papers on the theoretical, technological and experimental aspects of the design, development, and validation of various types of novel sensors printed or solution processed on diverse substrates, e.g. planar substrates, plastic, metal foils, paper etc.

Topics

- Intelligent Interactive Systems
- Stretchable/Shrinkable Sensors and Electronics
- Hybrid Systems-in-Foil (HySiF)
- Biomedical sensing devices
- Electronic textile/paper/skin
- Flexible/Printable Electronics in context with Circular Economy

- Organic/Inorganic/Hybrid Flexible Sensors and Electronics
- Printable batteries, energy harvesters
- Wearable sensors
- Sensors for health monitoring
- Printable displays, lighting sources
- Packaging

- Smart tags, RFID tags, etc.
- Modeling of printable sensors
- Manufacturing Techniques (including Printing)
- Emerging Materials for Flexible and Printable Systems
- 3D printing
- New developments in printed sensors

Important dates (tentative)

July 1, 2021:	Call for Papers (to appear in IEEE Sensor Journal)
Oct 1, 2021:	Deadline for Paper Submission
Dec 31, 2021:	Completion of First Review
March 31, 2022:	Completion of Final Review
May 2022:	Publication

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Submission and Peer Review of Papers

All papers shall undergo the standard IEEE Sensors Journal peer-review process. Manuscripts must be submitted online, via the *IEEE Manuscript Central^TM*, see http://mc.manuscriptcentral.com/sensors. When submitting, please indicate in the "Manuscript Type" roll down menu, and also by e-mail to Leigh Ann Testa, testa.l@ieee.org, that the paper is intended for the "IEEE FLEPS 2021 Conference" Special Issue. Authors are particularly encouraged to **suggest names of potential reviewers** for their manuscripts in the space provided for these recommendations in *Manuscript Central*. For manuscript preparation and submission, please follow the guidelines in the *Information for Authors* at the IEEE Sensors Journal web page, http://www.ieee-sensors.org/journals